

PATENT CLAIMS

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1. Etching solutions comprising hydrofluoric acid, an organic solvent, individually or as a mixture selected from the group consisting of ethylene glycol, propylene glycol, ethanol and glycerol, and water for the production of integrated circuits.
 - 10 2. Etching solutions according to Claim 1, comprising 5 - 20% by weight of hydrofluoric acid.
 - 15 3. Etching solutions according to Claim 1, comprising an organic solvent selected from the group consisting of ethylene glycol, propylene glycol, ethanol and glycerol.
 - SB27
 - 20 4. Etching solutions according to Claim 1, comprising, as organic solvent, ethylene glycol and glycerol in a mixing ratio of from 1:10 to 10:1.
 5. Etching solutions according to Claim 1, comprising, as organic solvent, ethylene glycol and glycerol in a mixing ratio of from 1:5 to 5:1.
 - 25 6. Etching solutions according to Claims 1 to 5, comprising water in an amount of from 1 to 20% by weight.
 - SB27
 - 30 7. Etching solutions according to Claims 1 to 6, comprising a mixture of high-purity individual components.
 8. Use of the etching solutions according to Claims 1 to 6 for the selective etching of doped silicate
35 layers.
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SB27